



SF325C 耐离子迁移型聚酰亚胺薄膜覆盖膜

SF325C Anti-ion Migration type PI film base coverlay

特点

- 优异的耐离子迁移性，不长枝状结晶。
- 不含卤素，阻燃性达到UL94 VTM-0级。
- 粘接强度高，尺寸稳定性、耐热性好。
- 溢胶量低，加工性好，适于快速压合和传统压合。
- 满足RoHS指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

FEATURES

- Excellent anti-ion Migration, no dendrite.
- Halogen free, Flammability UL94 VTM-0.
- High bonding strength, good dimensional stability and thermal resistance.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb, Hg, Cd, Cr⁶⁺, PBB, PBDE, etc..

应用领域

挠性印制电路板用覆盖膜。

APPLICATIONS

Coverlay for FPC.

性能表 GENERAL PROPERTIES

性能项目 Test Item	试验处理条件 Treatment Condition	单位 Unit	性能数据 Property Data		
			IPC 标准值* Standard	典型值 Typical Value	
				SF325C 0515	SF325C 1025
溢胶量 Resin Flow	A	mm	-	<0.15	<0.15
剥离强度 ¹ Peel Strength (90°) ¹	A	N/mm	≥0.7	1.2	1.4
	288℃,5s		≥0.53	1.1	1.3
热应力 ¹ Thermal Stress ¹	288℃,20s	-	-	无分层、无起泡 No delamination	无分层、无起泡 No delamination
尺寸稳定性 Dimensional Stability	MD TD 撕纸后 After peeling off the paper	%	±0.2	±0.1	±0.1
				±0.1	±0.1
耐化学性（剥离强度保持率） Chemical Resistance	After Chemical Exposure 暴露化学品后	%	≥80	>90	>90
体积电阻率（湿热） Volume Resistivity	C-96/35/90	MΩ-cm	≥10 ⁶	2.0×10 ⁸	2.5×10 ⁸
表面电阻（湿热） Surface Resistance	C-96/35/90	MΩ	≥10 ⁴	1.5×10 ⁶	1.5×10 ⁶
耐离子迁移性 Anti-ion Migration	C-1000/85/85, DC100V	-	-	通过 PASS	通过 PASS

注释 Explanations: C = 湿热处理条件 Humidity conditioning;

E = 恒温处理条件 Temperature conditioning.

1. 与铜箔光面压合再固化后测试。Testing after laminating with shining side of copper foil in suitable condition.

* Certified to IPC-4203/2 Epoxy adhesive on one or two sides of polyimide dielectric



SF325C 耐离子迁移型聚酰亚胺薄膜覆盖膜

SF325C Anti-ion Migration type PI film base coverlay

产品规格代码描述 Product Code Description

SF325C 05 15

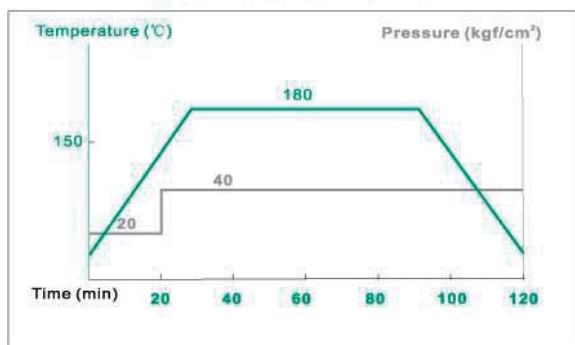


常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

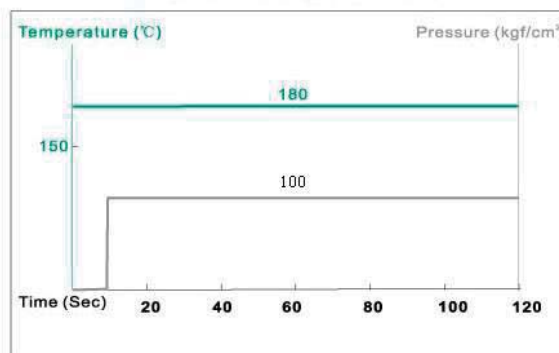
产品规格 Specifications	PI 膜厚度 (µ m) PI film Thickness (µ m)	胶粘剂厚度 (µ m) Adhesive Thickness (µ m)	应用领域 Applications
SF325C 0515	12.5	15	挠性印制电路板用覆 盖膜 Coverlay for FPC
SF325C 0520	12.5	20	
SF325C 0525	12.5	25	
SF325C 1025	25	25	
SF325C 1030	25	30	

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件是 160-170℃、60-90 分钟。
 The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-170℃ for 60-90min.

包装 PURCHASING INFORMATION

产品宽度 250+2/-0mm 或 500+2/-0mm，每卷 100+2/-0 米或 200+2/-0 米；其它规格、尺寸可根据客户要求而定。
 SF325C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

储存条件 STORAGE CONDITION

贮存在干燥的室内；以原始包装贮存在 4-10℃ 的冷藏室里，贮存期为三个月。
 Stored in the room of dryness. Three months when stored in the original packaging at 4-10℃.